

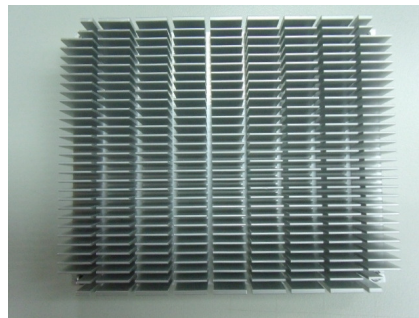
ETX-945GSE A0.2

Thermal Image Analysis Report

Report Number: 09E080029

Sample Configuration & Quantity Under Test

- CPU Board: AAEON ETX-945GSE A0.2
- CPU: Intel CPU N270/1.6GHz/FSB533MHz
- Memory: Kingston DDR2-667 KVR667D2S5/2G 2GB (7KEI2 D9HNL)
- HDD: Western Digital WD / 80GB
- Test Software: Windows XP / Run Prime95
- ATX Power Supply: Seventeam
- Cooler:



Test Result Summary

- Pass
 Fail
 Pass with Deviation

Comment: _____

2009-12-02

Issue Stamp

Wenyuan Yang

Manager

Jerry Tsai

Test Engineer

A. IR Image – Ho Spot Checking

1. Test Date: 02-12-2009

2. Test Product: ETX-945GSE

3. Test Site: AAEON QA Internal Lab.

4. Temperature Measurement:

IR Scanner: Infrared Camera
NIPPON AVIONICS CO., LTD.
Model: TVS-100
Date of Calibration: 09/17/09
Serial Number: 0179L2746

5. Test Condition:

1. Ambient temperature: Component Side-1: 24.1 °C, Solder Side: 23.1°C
2. ETX-945GSE without cooler

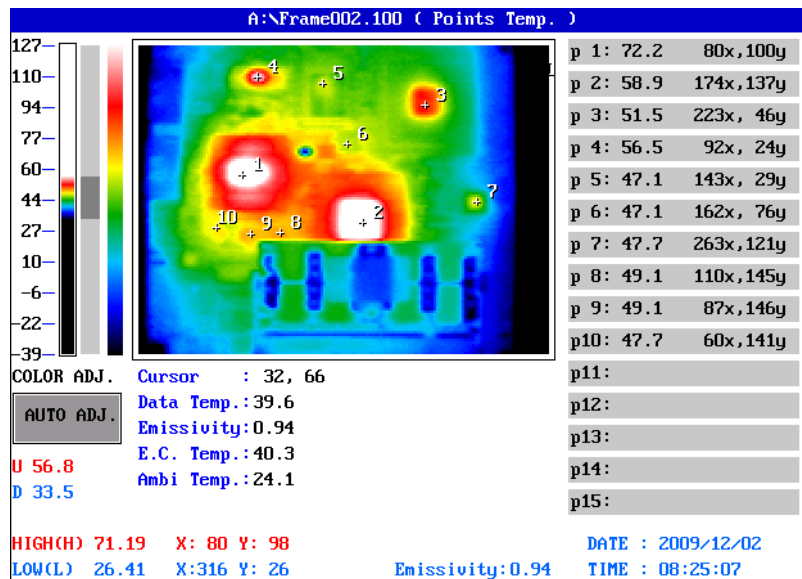
6. Test Software:

Windows XP / Run Prime 95

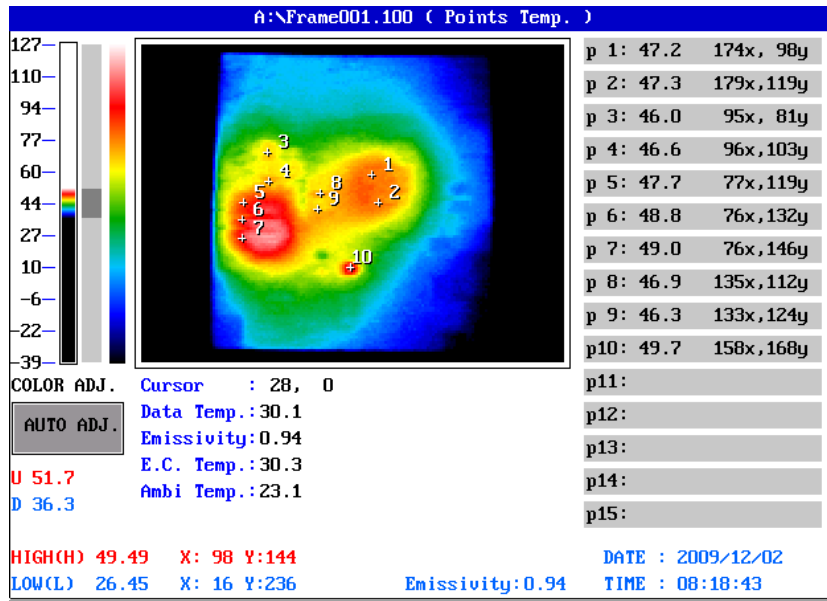
7. Take Picture Time:

After power on 2 hours

8. Infrared Image:



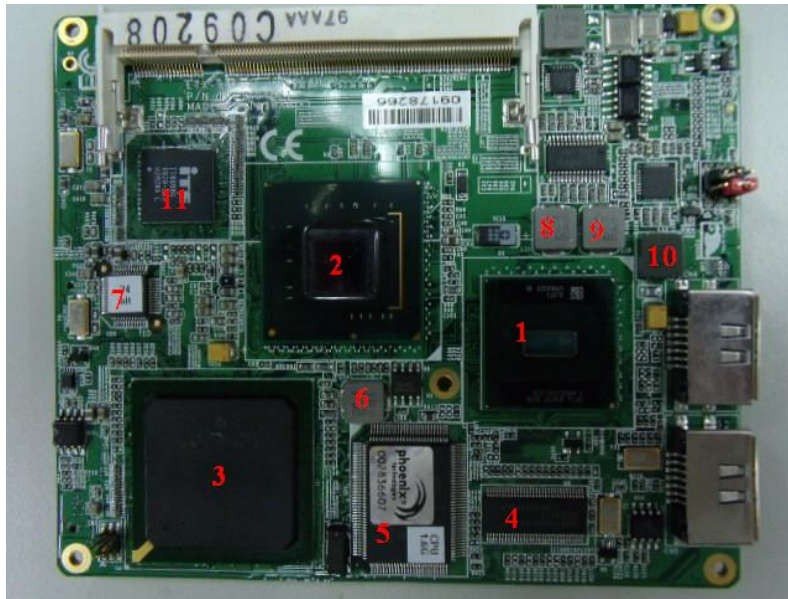
PIC 1. TOP view -1



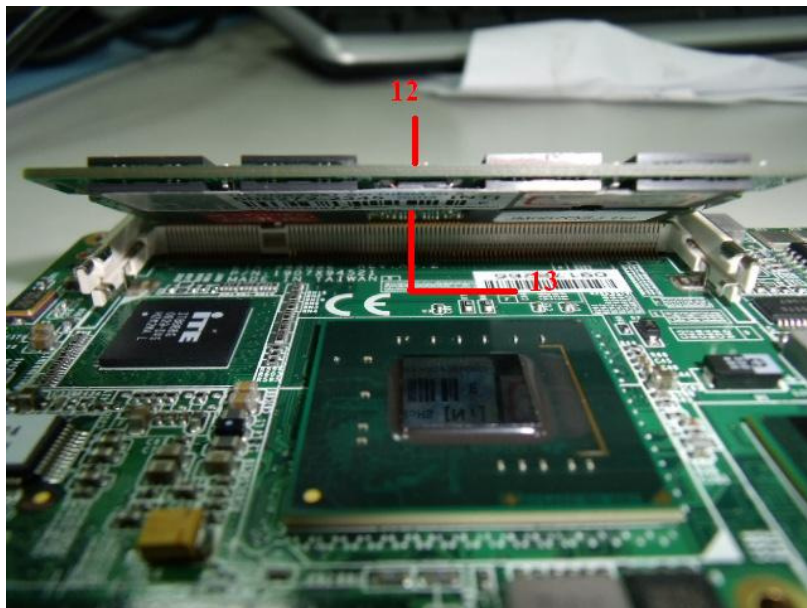
PIC 2. TOP view -2

B. Thermal Couple Measurement

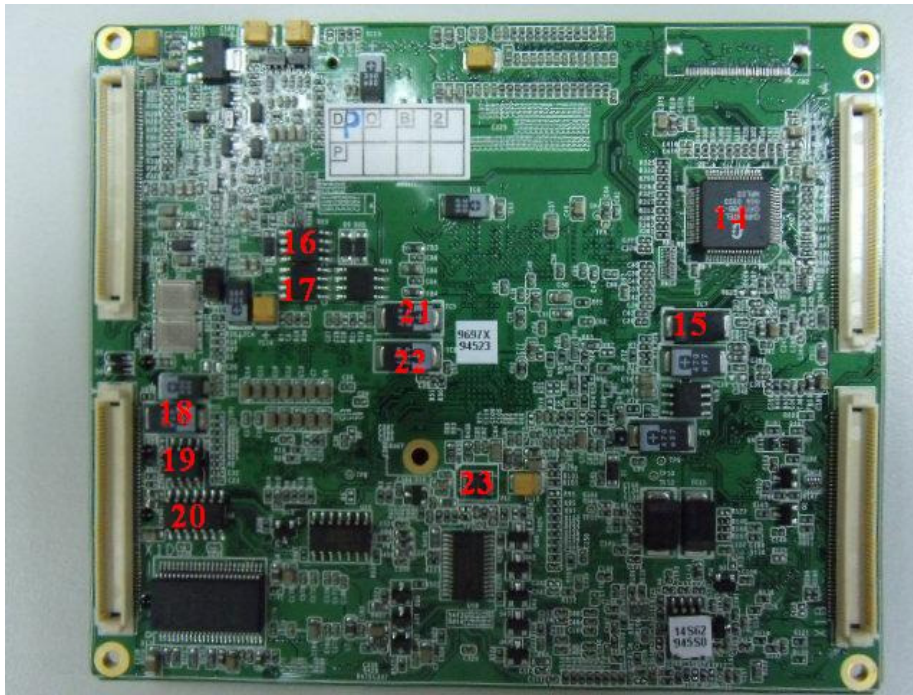
1. **Test Date:** 02-12-2009
2. **Test Product:** ETX-945GSE
3. **Test Site:** AAEON QA Internal Lab.
4. **Temperature Measurement:**
 - 40 Channel Thermal Recorder:
 - YOKOGAWA Inc,
 - Model: DA100-13-1D
 - Date of Calibration: 12/13/08
 - Serial Number: 12A323190
5. **Test Condition:**
 - Ambient temperature: 24dC
 - ETX-945GSE with cooler
6. **Test Software:**
 - Windows XP / Run Prime 95
7. **Take down Temperature Time:**
 - After power on 2 hours
8. **Measurement Spots of Terminal Couple**



PIC 3. Thermal Couple Location on Component Side



PIC 4. Thermal Couple Location on DIMM



PIC 5. Thermal Couple Location on Solder Side

9. Thermal profile data:

Point	Designator	Description	Tc *1 (°C)	Tm *2 (°C) Measured Under	
				24.0°C	60°C
01	U1	(TF)IntelCPU.Diamondville.N270.1.6GHz/FSB533MHz.FCBGA8.43 7Pins.STEPPING CODE:SLB73.AU80586GE025D	95	46.3	82.3
02	U3	(TF)IC.SMD.Intel 945GSE Express Chipset.Intel.QG82945GSE SLB2R	105	53.7	89.7
03	U4	(TF)IC.SMD.Chipset ICH7M.Intel.NH82801GBM SL8YB	100	44.8	80.8
04	U9	(TF)IC.SMD.TSSOP64P.CLOCKGENERATOR.IDT.9LPRS501PG LF	100	56.5	92.5
05	U24	(TF)IC.SMD.PQFP 128Pin.LPC Super I/O.Winbond.W83627HG-AW A version	100	51.5	87.5
06	L14	(TF)COIL.1uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=9mohm.Irms=11 Amp.GOTREND.GSTC063P-1R0MN	125	57.5	93.5
07	U26	(TF)IC.SMD LQFP 48Pin.6 Channel AC'97 Audio Codec.REALTEK.ALC655-LF	100	53.6	89.6
08	L11	(TF)COIL.1uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=9mohm.Irms=11 Amp.GOTREND.GSTC063P-1R0MN	125	58.9	94.9
09	L10	(TF)COIL.1uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=9mohm.Irms=11 Amp.GOTREND.GSTC063P-1R0MN	125	59.5	95.5

10	L13	(TF)COIL.0.33uH.Irms=20A.Isat=30A.20%.SMD(7.3x6.8x3.0).2pin. RDC=3.9m Ohm.GOTREND.GSTC063P-R33MN	125	56.4	92.4
11	U29	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L	100	49.5	85.5
12	DDR	Kingston DDR2-667 KVR667D2S5/2G 2GB (7KEI2 D9HNL)	85	49.5	85.5
13	DDR	Kingston DDR2-667 KVR667D2S5/2G 2GB (7KEI2 D9HNL)	85	52.7	88.7
14	U27	(TF)IC.SMD.LQFP 64Pin.LVDS Transmitter.CHRONTEL.CH7308B-TF	115	50.2	86.2
15	TC7	(TF)SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221EY	105	50.5	86.5
16	U15	(TF)Dual N-Channel.SMD SO-8.2.5V MOSFET.APEC.AP9926GM	125	46.6	82.6
17	U17	(TF)PWR.MOSFET.N-Channel 30V SO-8.VISHAY.Si4420DY-T1-E3	125	47.6	83.6
18	TC1	(TF)POSCAP.470uF.2.5V.20%.D2(7.3*4.3*1.8).9mohm.3900mA.SM D.SANYO.2R5TPE470M9	135	53.6	89.6
19	U28	(TF)IC.SMD.SOIC-8P.2K Serial EEPROM.ATMEL.AT24C02BN-SH-T	125	52.7	88.7
20	U8	(TF)IC.SMD SO.14Pin.PHILIPS.74LVCO7AD-T	125	51.5	87.5
21	TC5	(TF)POSCAP.470uF.2.5V.20%.D2(7.3*4.3*1.8).9mohm.3900mA.SM D.SANYO.2R5TPE470M9	135	47.3	83.3
22	TC6	(TF)POSCAP.330uF.2.5V.20%.C2(6*3.2*1.8).12mohm.3300mA.SMD .SANYO.2R5TPE330MCC2	135	46.9	82.9
23	U12	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF	125	50.7	86.7

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:
 - Fail : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - Margin : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - Pass : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.